
PRODUCT CHANGE NOTICE

**Alternate Bond Wire Material
for Assembly of the Listed
Intersil QFN Packaged
Products**

**Refer to:
PCN12095**

Date: December 10, 2012

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To: Our Valued Intersil Customer

Subject: **Alternate Bond Wire Material for Assembly of the Listed Intersil QFN Packaged Products –Carsem (CAS) Ipoh, Malaysia**

This notice is to inform you that Intersil has qualified copper bond wire as an alternate to the gold bond wire currently used for assembly of the listed QFN (Quad Flat No-lead) packaged products at the Carsem (CAS) facility located in Ipoh, Malaysia. The advantages of copper bond wire include improved electrical conductivity of the wire, slower intermetallic growth, reduced wire sweep and equivalent reliability performance. This action will expand current capabilities and capacities to optimize Intersil's ability to meet customer's delivery requirements. As of this notice, all product and package specific qualification activities are complete.

Products affected:

ISL62882CHRTZ	ISL62883CHRTZ	ISL95870BHRZ	ISL95870BIRZ
ISL62882CHRTZ-T	ISL62883CHRTZ-T	ISL95870BHRZ-T	ISL95870BIRZ-T

The Carsem (CAS) facility is ISO 9001:2008 and ISO/TS 16949:2009 certified and currently qualified as a primary supplier to Intersil for assembly of QFN packaged products using both gold and copper bond wire material. There will be no change in the mold compound, die attach, lead frame, or package outline drawing (POD). The qualified material set combinations for assembly and other key items are as follows:

Key Items	CAS Current	CAS New (Alternate)
Mold Compound	Sumitomo EME-G770	Sumitomo EME-G770
Die Attach	QMI 519	QMI 519
Bond Wire	1.0 mil Gold (Au)	1.0 mil Copper/Palladium (CuPd)
Moisture Sensitivity Level	1 or 2	3
Device Marking - Site Code	F	X

The qualification plan for copper bond wire assembly is designed using JEDEC and other applicable industry standards to confirm there is no impact to form, fit, function, or interchangeability of the product. A summary of the copper bond wire assembly qualification results is included for reference. The remainder of the manufacturing operations (wafer fabrication, package level electrical testing, shipment, etc.) will continue to be processed to previously established conditions and systems.

Products affected by this change that are assembled using either gold or copper bond wire material are identifiable via Intersil's internal traceability system and by the assembly site code (country of assembly) when marked on the devices. The site code for product assembled at CAS with copper bond wire is "X". The site code for product assembled at CAS with gold bond wire is "F".

Intersil will take all necessary actions to conform to agreed upon customer requirements and to ensure the continued high quality and reliability of products being supplied. Customers may expect to receive product assembled using either gold or copper bond wire beginning *ninety* days from the date of this notification or earlier with approval.

If you have concerns with this change notice, Intersil must hear from you promptly. Please contact the nearest Intersil Sales Office or call the Intersil Corporate line at 1-888-468-3774, in the United States, or 1-321-724-7143 outside of the United States.

Regards,

Jon Brewster

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PCN12095

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PCN12095 –CAS Reliability Qualification Summary

Device: ISL62883CHRTZ-T (40L 5x5 TQFN)						
Stress / Conditions	Duration	Test lots			Control Lot	Result
		Lot #1	Lot #2	Lot #3		
MSL classification	L3 PBFree	0/22	0/22	0/22	0/22	PASS
uHAST 130C / 85% RH L3 PBFree	96 Hrs	0/26	0/26	0/26	0/78	PASS
Temp Cycle -65C to +150C L3 PBFree	500 cyc	0/80	0/80	0/80	0/80	PASS

Device: ISL95870BHRZ-TS2705 (20L 3X4 QFN)						
Stress / Conditions	Duration	Test lots			Control Lot	Result
		Lot #1	Lot #2	Lot #3		
MSL classification	L3 PBFree	0/22	0/22	0/22	0/22	PASS
uHAST 130C / 85% RH L3 PBFree	96 Hrs	0/26	0/26	0/26	0/78	PASS
Temp Cycle -65C to +150C L3 PBFree	500 cyc	0/80	0/80	0/80	0/80	PASS